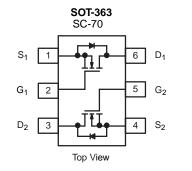
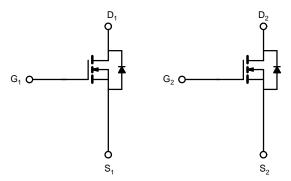
## TSM2N7002KDCU6 RF



## Dual N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (mA)			
60	1.8 at V <sub>GS</sub> = 10 V	350			





#### **FEATURES**

- Halogen-free According to IEC 61249-2-21
  Definition
- •Low On-Resistance: 1.8  $\,\Omega$
- Low Threshold: 2 V (typ.)
- •Low Input Capacitance: 30 pF
- Fast Switching Speed: 25 ns
- Low Input and Output Leakage
- TrenchFET<sup>®</sup> Power MOSFET
- 1200V ESD Protection
- Compliant to RoHS Directive 2002/95/EC

#### **BENEFITS**

- Low Offset Voltage
- Low-Voltage Operation
- · Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage

#### **APPLICATIONS**

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted									
Parameter		Symbol	Limit	Unit					
Drain-Source Voltage		V <sub>DS</sub>	60	V					
Gate-Source Voltage		V <sub>GS</sub>	± 20						
Continuous Drain Current (T <sub>.1</sub> = 150 °C) <sup>b</sup>	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	350	mA					
Continuous Drain Current $(T_j = 150 \text{ °C})^2$	T <sub>A</sub> = 100 °C		230						
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	900						
Davian Diasin atiant	T <sub>A</sub> = 25 °C	PD	0.35	W					
Power Dissipation <sup>b</sup>	T <sub>A</sub> = 100 °C	۲D	0.14	vv					
Maximum Junction-to-Ambient <sup>b</sup>		R <sub>thJA</sub>	350	°C/W					
Operating Junction and Storage Temperature Range		T <sub>J,</sub> T <sub>stg</sub>	- 55 to 150	°C					

Notes:

a. Pulse width limited by maximum junction temperature.

b. Surface Mounted on FR4 board.



COMPLIANT HALOGEN

FREE

ailabl

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter		Test Conditions	Limits			
	Symbol		Min.	Typ. <sup>a</sup>	Max.	Unit
Static			•		•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 10 \mu A$	60			V
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	1		2.5	
Gate-Body Leakage		$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 10	μA
	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 15 V$			1	
		$V_{DS} = 0 V, V_{GS} = \pm 10 V$			± 150	nA
		$V_{DS} = 0 V, V_{GS} = \pm 10 V, T_{J} = 85 °C$			± 1000	
	-	$V_{DS} = 0 V, V_{GS} = \pm 5 V$			± 100	
Zero Gate Voltage Drain Current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			500	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 7.5 V	800			mA
		$V_{GS}$ = 4.5 V, $V_{DS}$ = 10 V	500			
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 500 mA		1.8		Ω
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 200 mA		3		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 200 mA	100			mS
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 200 mA, V <sub>GS</sub> = 0 V			1.3	V
Dynamic <sup>a</sup>					•	
Total Gate Charge	Qg	$V_{DS}$ = 10 V, $V_{GS}$ = 4.5 V I <sub>D</sub> $\cong$ 250 mA		0.6	0.8	nC
Input Capacitance	C <sub>iss</sub>			30		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$		6		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		2.5		
Switching <sup>a, b, c</sup>						
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 30 V, R <sub>I</sub> = 150 Ω			25	
Turn-Off Time	t <sub>d(off)</sub>	$I_D \cong 200 \text{ mA}, V_{GEN} = 10 \text{ V}, R_G = 10 \Omega$			35	ns

Notes:

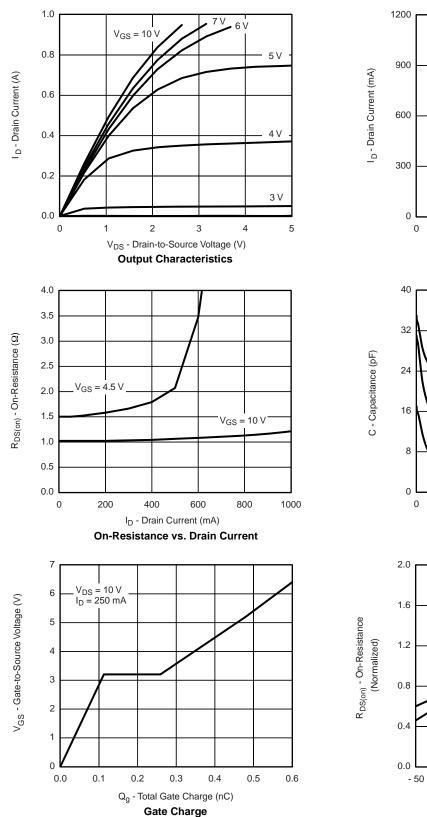
a. For DESIGN AID ONLY, not subject to production testing.

b. Pulse test: PW  $\leq$  300 µs duty cycle  $\leq$  2 %.

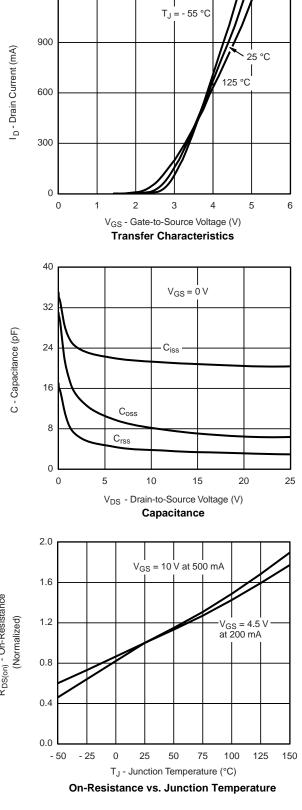
c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



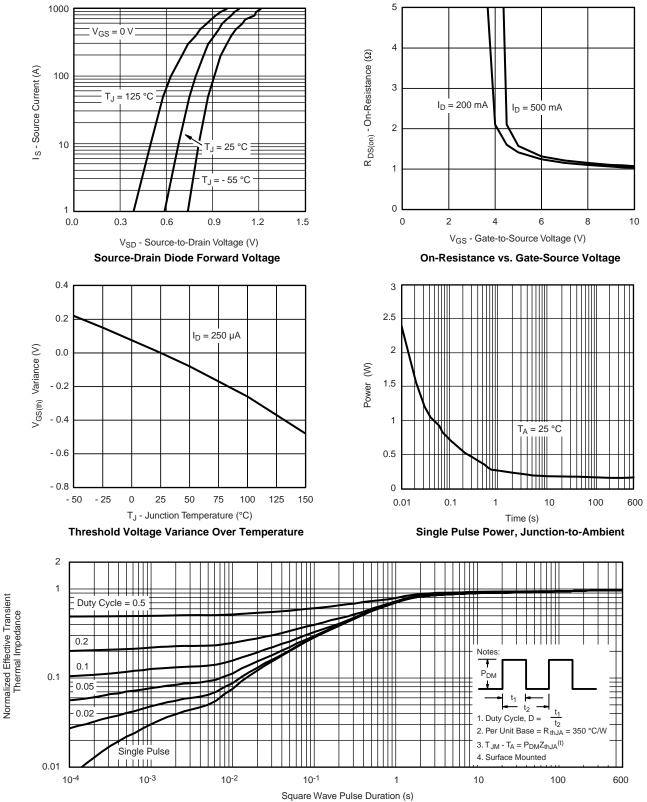


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



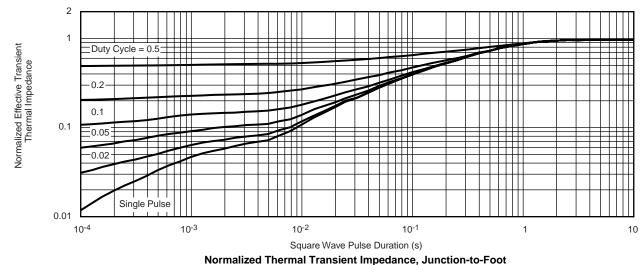


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient





## **THERMAL RATINGS** ( $T_A$ = 25 °C, unless otherwise noted)

#### Note

• The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Foot (25 C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



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